### SN5426, SN54LS26, SN7426, SN74LS26 QUADRUPLE 2-INPUT HIGH-VOLTAGE INTERFACE POSITIVE-NAND GATES

DECEMBER 1983-REVISED MARCH 1988

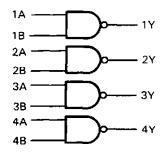
For Driving Low-Threshold-Voltage MOS Inputs

#### description

These 2-input open-collector NAND gates feature high-output voltage ratings for interfacing with low-threshold-voltage MOS logic circuits or other 12-volt systems. Although the output is rated to withstand 15 volts, the V<sub>CC</sub> terminal is connected to the standard 5-volt source.

The SN5426 and SN54LS26 are characterized for operation over the full military temperature range of  $-55\,^{\circ}\text{C}$  to 125 $^{\circ}\text{C}$ . The SN7426 and SN74LS26 are characterized for operation from  $0\,^{\circ}\text{C}$  to  $70\,^{\circ}\text{C}$ .

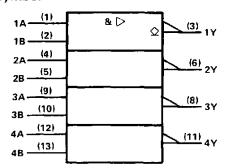
#### logic diagram



#### positive logic

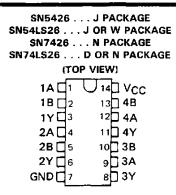
$$Y = \overline{AB}$$

#### logic symbol†

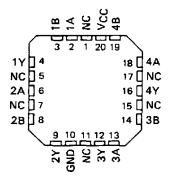


<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

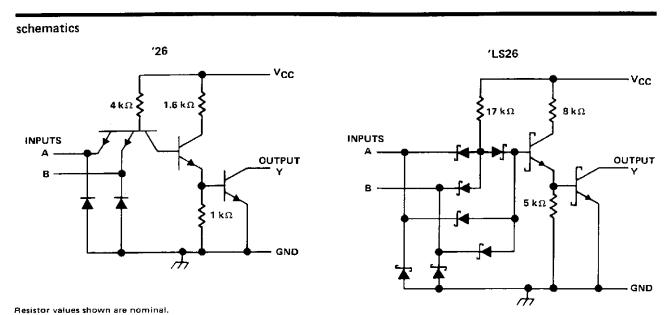


SN54LS26 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

### SN5426, SN54LS26, SNSN7426, SN74LS26 QUADRUPLE 2-INPUT HIGH-VOLTAGE INTERFACE POSITIVE-NAND GATES



#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage , VCC (see Note 1)
Input voltage: '26
'LS26 7 V
Operating free-air temperature: SN54'
SN74′
Storage temperature range

NOTE 1: Voltage values are with respect to network ground terminal.

#### recommended operating conditions

	S	\$N54L\$26			SN74LS26			
	MIN	NOM	MAX	MIN	MOM	мах	UNIT	
V <sub>CC</sub> Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
V <sub>JH</sub> High-level input voltage	2			2			V	
VIL Low-level input voltage			0.7			0.8	V	
VOH High-level output voltage			15			15	V	
OL Low-level output current			4			8	mA	
TA Operating free-air temperature	<b>– 55</b>		125	0		70	°C	

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS <sup>†</sup>				26	S	N74LS2	26	UNIT
PANAIVIE I EN						MAX	MIN	TYP‡	MAX	UNIT
Vικ	V <sub>CC</sub> = MIN,	I <sub>1</sub> = 18 mA				- 1.5			<b>– 1.5</b>	V
	V <sub>CC</sub> = MIN,	VIL = MAX,	V <sub>OH</sub> = 12 V			50			50	μА
юн	VCC = MIN,	VIL = MAX,	V <sub>OH</sub> = 15 V			1			1	mA
17	V <sub>CC</sub> = MIN,	V <sub>1H</sub> = 2 V,	I <sub>OL</sub> = 4 mA		0.25	0.4		0.25	0.4	
V <sub>O</sub> L	V <sub>CC</sub> = MIN,	V <sub>1H</sub> = 2 V,	IOL = 8 mA					0.35	0.5	V
l)	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 7 V				0.1			0.1	mΑ
ΊΗ	VCC = MAX,	V <sub>IH</sub> = 2.7 V				20			20	μΑ
ΉL	V <sub>CC</sub> = MAX,	V <sub>IL</sub> = 0.4 V	<u> </u>			- 0.4			- 0.4	mA
ССН	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0			0.8	1.6		8.0	1.6	mA
ICCL	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 4.5 V			2.4	4.4		2,4	4.4	

 $<sup>^{\</sup>dagger}$  For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. ‡ All typical values are at  $V_{CC} = 5$  V,  $T_A = 25$ °C.

#### switching characteristics, VCC = 5 V, TA = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN T	ГҮР	мах	UNIT
<sup>‡</sup> PLH	A or B		$R_1 = 2 k\Omega$ , $C_1 = 15 pF$		17	32	ns
t <b>P</b> HL	7016	'	11 - 2 Ki2, C[ - 15 pr		15	28	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

### SN5426, SN7426 QUADRUPLE 2-INPUT HIGH-VOLTAGE INTERFACE POSITIVE-NAND GATES

#### recommended operating conditions

		SN5426			SN7426			
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
VCC Supply voltage	4.5	5	5.5	4.75	5	5.25		
VIH High-level input voltage	2			2			V	
VIL Low-level input voltage			0.8			0.8	>	
VOH High-level output voltage			15			15	>	
IOL Low-level output current			16			16	mΑ	
TA Operating free-air temperature	<b>– 55</b>		125	0		70	°C	

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS†	SN5426	\$N7426	
PARAMETER	TEST CONDITIONS.	MIN TYP‡ MAX	MIN TYP‡ MAX	UNIT
VIK	$V_{CC} = MIN, i_{\parallel} \approx -12 \text{ mA}$	- 1.5	-1.5	V
	$V_{CC} = MIN$ , $V_{IL} = 0.8 \text{ V}$ , $V_{OH} = 12 \text{ V}$		50	
ЮН	$V_{CC} = MIN$ , $V_{IL} = 0.7 \text{ V}$ , $V_{OH} = 12 \text{ V}$	50		μΑ
	VCC = MIN. VIL = 0.8 V, VOH = 15 V		1	
	$V_{CC} = MIN$ , $V_{IL} = 0.7 \text{ V}$ , $V_{OH} = 15 \text{ V}$	1		mA
VoL	$V_{CC} = MIN$ , $V_{IH} = 2 V$ , $I_{OL} = 16 mA$	0.4	0.4	V
lj .	V <sub>CC</sub> = MAX, V <sub>I</sub> = 5.5 V	1	1	mA
IH	V <sub>CC</sub> = MAX, V <sub>1</sub> = 2.4 V	40	40	μΑ
IL.	$V_{CC} = MAX$ , $V_{\parallel} = 0.4 \text{ V}$	-1.6	-1.6	mΑ
Іссн	$V_{CC} = MAX$ , $V_I = 0$	4 8	4 8	mA
CCL	$V_{CC} = MAX$ , $V_I = 4.5 V$	12 22	12 22	mA

<sup>&</sup>lt;sup>†</sup>For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

## switching characteristics, VCC = 5 V, TA = 25°C (see note 2)

PAR	RAMETER	FROM (INPUT)	TQ (TUPTUO)	TEST CON	MIN	TYP	MAX	UNIT	
	<sup>t</sup> PLH	A or B	Y	R <sub>1</sub> = 1 kΩ,	C <sub>1</sub> = 15 pF	Ī	16	24	ns
	<sup>t</sup> PHL :						11	17	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

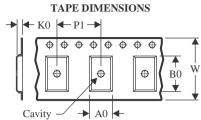
 $<sup>^{\</sup>ddagger}$ All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25 °C.

## **PACKAGE MATERIALS INFORMATION**

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#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	_	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS26DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

**PACKAGE MATERIALS INFORMATION** 

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS26DR	SOIC	D	14	2500	356.0	356.0	35.0

www.ti.com 9-Aug-2022

#### **TUBE**



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-7602001VDA	W	CFP	14	1	506.98	26.16	6220	NA
7602001DA	W	CFP	14	1	506.98	26.16	6220	NA
JM38510/32102BDA	W	CFP	14	1	506.98	26.16	6220	NA
M38510/32102BDA	W	CFP	14	1	506.98	26.16	6220	NA
SN74LS26D	D	SOIC	14	50	506.6	8	3940	4.32
SN74LS26DE4	D	SOIC	14	50	506.6	8	3940	4.32
SN74LS26N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS26N	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54LS26W	W	CFP	14	1	506.98	26.16	6220	NA

## W (R-GDFP-F14)

## CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a certain is using glass int.
  Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
  Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



## D (R-PDSO-G14)

#### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



# D (R-PDSO-G14)

## PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



## N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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